



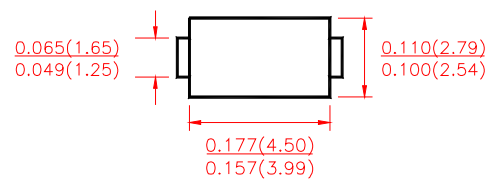
技术参数规格书

主要电气参数

IF	5.0A
VRRM	20-100V
IFSM	100A
IR	500uA
VF	0.55-0.85V
Tj max	150°C

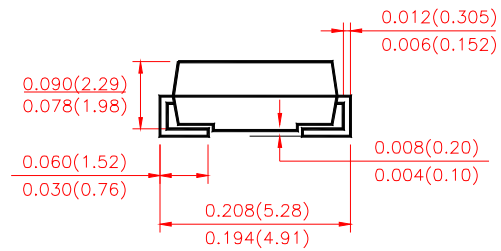
封装尺寸规格:

DO-214AC(SMA)



特性:

- 贴片小型外观
- 专为 SMT 自动贴片设计
- SKY 芯片
- 低正向压降
- 耐瞬间正向浪涌电流冲击
- 耐高温焊接：引脚耐焊接热条件为 260°C/10 秒
- 符合 EU RoHS 2002/95/1 指令要求

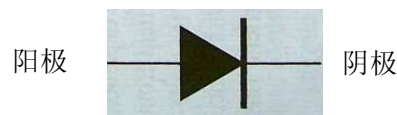


Dimensions in inches and (millimeters)

外观参数:

- 封装：符合 JEDEC DO-214AC, 平面芯片结合外部塑封
- 引脚：表面镀锡，可焊性参照 MIL-STD-750, Method 2026
- 标准包装：12mm 包装带
- 重量：约 0.0725 克
- 极性标示：激光打印，阴极标有阴极线条

电气符号:





SS52A THRU SS510A

额定参数表：

如无特殊说明，参数均在温度 25℃ 条件下测试。单相，半波，60Hz，阻性或感性负载。对于容性负载，电流参数需下降 20%

	SYMBOLS	SS52 SK52	SS53 SK53	SS54 SK54	SS55 SK55	SS56 SK56	SS58 SK58	SS59 SK59	SS510 SK510	UNIT	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	30	40	50	60	80	90	100	Volts	
Maximum RMS Voltage	V_{RMS}	14	21	28	35	42	56	63	70	Volts	
Maximum DC Blocking Voltage	V_{DC}	20	30	40	50	60	80	90	100	Volts	
Maximum Average Forward Rectified Current at T_L see figure 1 $T_L=105^\circ\text{C}$	$I_{(AV)}$	5.0								Amps	
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	100								Amps	
Maximum Instantaneous Forward Voltage @ 5.0A(Note1)	V_F	0.55			0.75		0.85			Volts	
Maximum DC Reverse Current at rated DC Blocking Voltage per element	I_R	$T_A = 25^\circ\text{C}$ 0.5				$T_A = 100^\circ\text{C}$ 20.0					mA
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$	55								°C/W	
	$R_{\theta JL}$	12									
Operating Junction Temperature	T_J	(-55 to +150)				(-55 to +150)					°C
Storage Temperature Range	T_{STG}	(-55 to +150)									°C

成品出货质量水准：

基于 MIL-STD-105E LEVEL II 标准，OQC 为：

Item	Critical	Major	Minor
AQL (%)	0.01	0.10 (Electrical)	1.00
		0.25 (Physical)	



典型特性曲线图:

如无特殊说明, 参考温度均为 $T_c = 25^\circ\text{C}$

RATING AND CHARACTERISTIC CURVES SS52 THRU SS510

